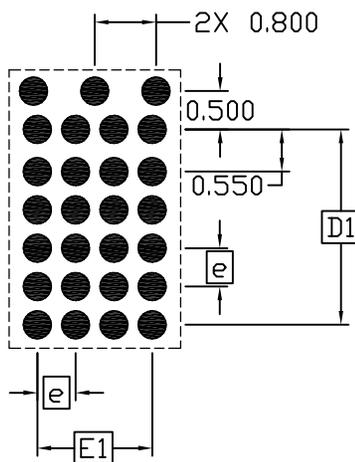
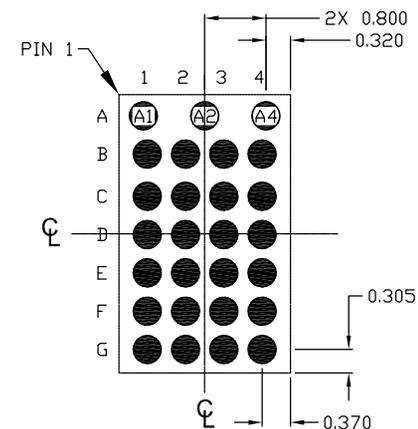


RECOMMENDED LAND PATTERN

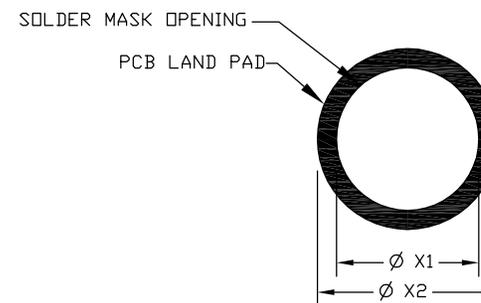


PACKAGE OVERLAY



DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
D1		2.550 BSC		.10039 BSC		
E1		1.500 BSC		.05906 BSC		
e		0.500 BSC		.01969 BSC		
N		27 BALLS		27 BALLS		

PAD DETAIL INFORMATION



DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
X1	0.230	0.280	0.330	.00906	.01102	.01299
X2	0.360	-	-	.01417	-	-

NOTES:

1. REFERENCE PKG. OUTLINE: 21-0926
2. LAND PATTERN COMPLIES TO: IPC7351A.
3. ALL DIMENSIONS APPLY TO PbFREE (+) PKG. CODE ONLY.
4. ALL DIMENSIONS IN MM.

-DRAWING NOT TO SCALE-



This document (including dimensions, notes & specs) is a recommendation based on typical circuit board manufacturing parameters. Since land pattern design depend on many factors unknown to Maxim (eg. user's board manufacturing specs), user must determine suitability for use.

This document is subject to change without notice.

Contact technical support at <http://www.maximintegrated.com/support> for further questions.

TITLE:
PACKAGE LAND PATTERN,
[C272B3+1] WLCSP

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